

TG2030 超軟導熱矽膠 Ultra Soft Thermal Pad



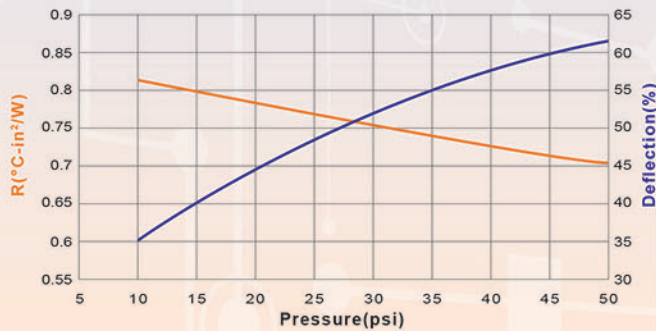
產品特性 Features

- Low oil-bleed 低出油量
- Ultra soft and high compressibility 超軟與高壓縮性
- Electrical insulation 絕緣耐電壓高
- As a buffer in electronics 幫助機構之緩衝

產品應用端 Applications

- Electronic components: IC, CPU, MOS, LED, Mother Board, Power Supply, Heat Sink, LCD-TV, Notebook, PC, Telecom Device, Wireless Hub, DDR II Module, DVD Applications, Hand-set applications etc.

熱阻抗VS.壓力VS.變形量示意圖 Thermal Resistance VS. Pressure VS. Deflection

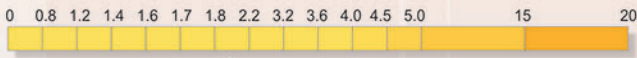


Pressure (psi)	R (°C-in²/W)	Deflection (%)
10	0.82	35
30	0.76	53
50	0.71	62

產品物性 Properties

● REACH Compliant 符合REACH規範 ● RoHS Compliant 符合RoHS規範 ● UL Compliant 符合UL規範

Thermal Conductivity 導熱係數 : 2.0 W/mK



Hardness 軟硬度 : 30 (Shore 00)



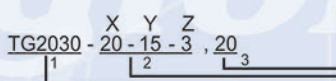
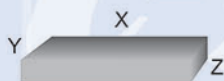
Testing sample thickness: 1.0mm

In "Thermal resistance V.S. Pressure V.S. Deflection" chart, TG2030 provides low thermal impedance. The pressure gets higher, the thermal impedance gets lower, and deflection percentage gets higher. TG2030 provides good compliance and softness.

Properties	TG2030	Unit	Tolerance	Test Method
Thermal Conductivity 導熱係數	2	W / mK	±0.2	ASTM D5470
Thickness 厚度	0.5~5.0	mm	-	ASTM D374
	0.0197~0.1969	inch	-	ASTM D374
Color 顏色	White白	-	-	Visual目視
Flame Rating 耐燃等級	V-0	-	-	UL 94
Dielectric Breakdown Voltage 耐電壓	16	KV / mm	±1.6	ASTM D149
Weight Loss 重量損失	<1	%	-	ASTM E595
Density 密度	2.4	g / cm³	±0.2	ASTM D792
Working Temperature 工作溫度	-45~+200	°C	-	-
Volume Resistance 體積阻抗	>10 ¹⁰	Ohm-m	-	ASTM D257
Elongation 延展率	300	%	-	ASTM D412
Tensile Strength 抗拉強度	1	Kgf / cm²	-	ASTM D412
Standard Shape 標準形狀	Sheet ones單片狀	-	-	-
Hardness 硬度	30	Shore 00	±10	ASTM D2240

Need samples? 樣品需求?

Pre-cut for different shapes 可依需求沖型裁切



1. Choose the P/N
2. Fill into size: X, Y, Z
3. Fill the quantity you need